

NCE P-Channel Enhancement Mode Power MOSFET

Description

The NCEA2301 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

General Features

• $V_{DS} = -20V, I_{D} = -3A$

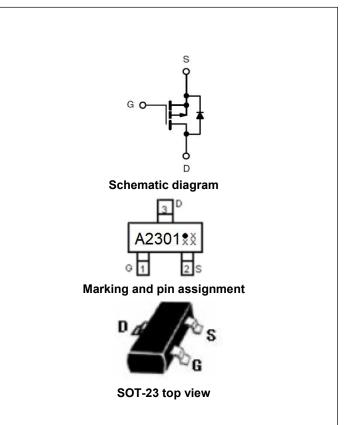
 $R_{DS(ON)} < 140 m\Omega$ @ V_{GS} =-2.5V

 $R_{DS(ON)}$ < 110m Ω @ V_{GS} =-4.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package
- AEC-Q101 qualified

Application

- Automotive application
- PWM applications
- Load switch
- Power management



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
A2301 [*] X	NCEA2301	SOT-23	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _G s	±12	V
Drain Current-Continuous	I _D	-3	А
Drain Current -Pulsed (Note 1)	I _{DM}	-12	А
Maximum Power Dissipation	P _D	1	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	ReJA	125	°C/W

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						



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NCEA2301

Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250µA	-20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V,V _{GS} =0V	-	-	-1	μA
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			'		1	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-0.4	-0.7	-1	V
Davis Course On Otata Davistana		V _{GS} =-4.5V, I _D =-3A	-	64	110	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-2.5V, I _D =-2A	-	89	140	mΩ
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-2A	5	-	-	S
Gate resistance	R _G	F=1.0MHz	-	6.6	-	Ω
Dynamic Characteristics (Note4)			•	•		
Input Capacitance	C _{lss}	V _{DS} =-10V,V _{GS} =0V, F=1.0MHz	-	841	-	PF
Output Capacitance	Coss		-	75	-	PF
Reverse Transfer Capacitance	C _{rss}	F-1.UIVIDZ	-	47	-	PF
Switching Characteristics (Note 4)				•		
Turn-on Delay Time	t _{d(on)}		-	11	-	nS
Turn-on Rise Time	tr	V _{DD} =-10V,I _D =-1A	-	35	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-4.5V, R_{GEN} =10 Ω	-	30	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg	\/ - 40\/ - 24	-	7.4	-	nC
Gate-Source Charge	Q _{gs}	V_{DS} =-10V, I_{D} =-3A, V_{GS} =-4.5V	-	1	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} 4.5V	-	1.9	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =1.3A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is		-	_	-3	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.



4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

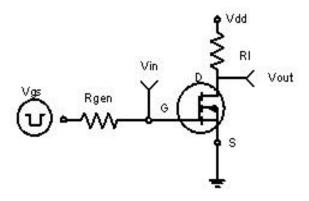
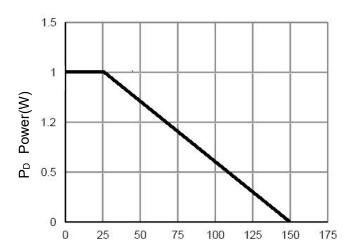


Figure 1:Switching Test Circuit



T-Junction Temperature(°C)

Figure 3 Power Dissipation

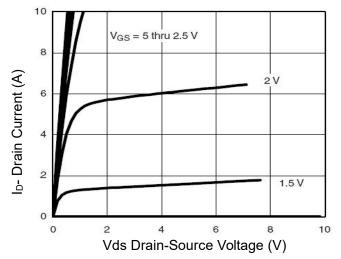


Figure 5 Output Characteristics

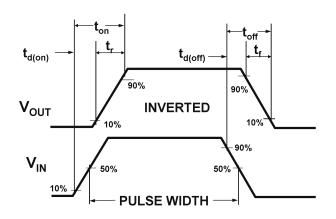
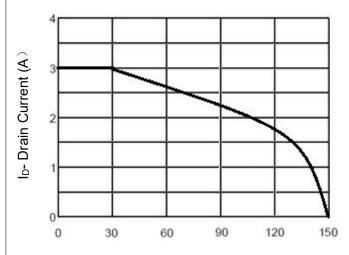


Figure 2:Switching Waveforms



T_J-Junction Temperature(°C)

Figure 4 Drain Current

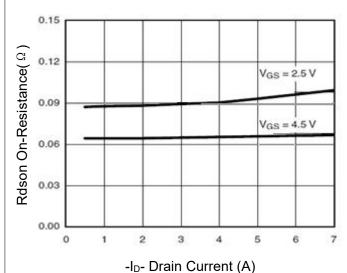
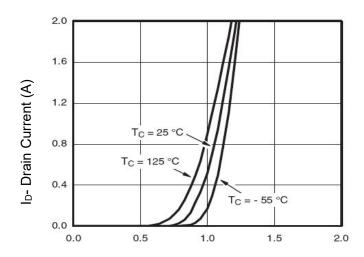


Figure 6 Drain-Source On-Resistance

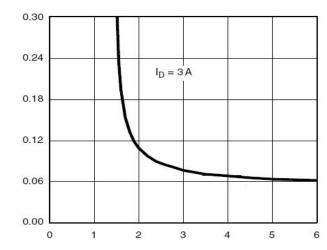


Rdson On-Resistance((2))



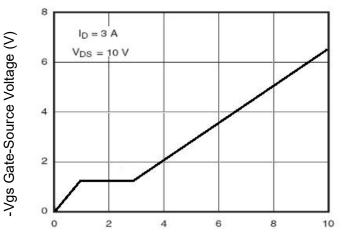
Vgs Gate-Source Voltage (V)

Figure 7 Transfer Characteristics

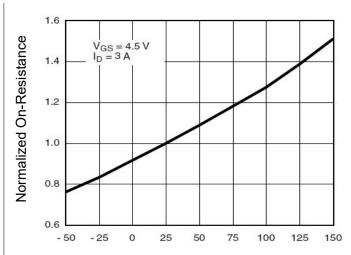


-Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

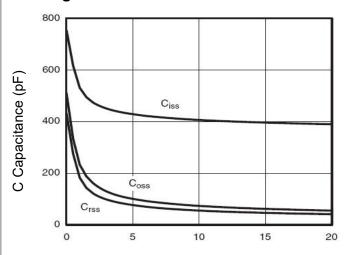


Qg Gate Charge (nC) Figure 11 Gate Charge



T_J-Junction Temperature(°C)

Figure 8 Drain-Source On-Resistance



-Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds

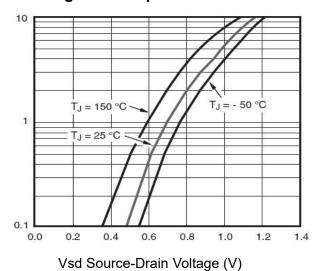
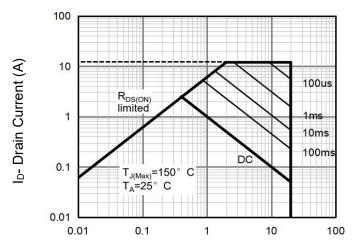


Figure 12 Source- Drain Diode Forward

Is- Reverse Drain Current (A)





Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area

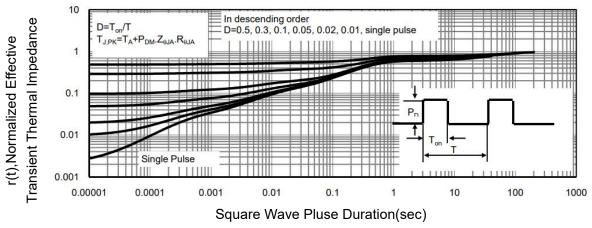
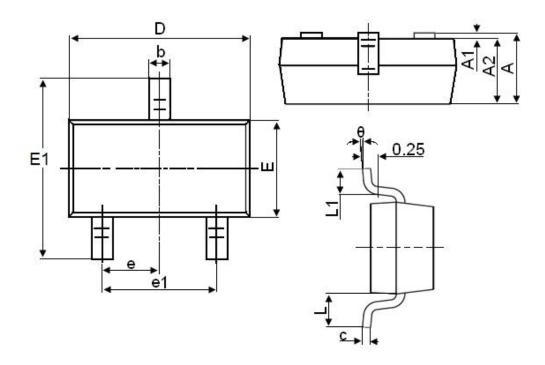


Figure 14 Normalized Maximum Transient Thermal Impedance



SOT-23 Package Information



Cymphol	Dimensions in Millimeters				
Symbol	MIN.	MAX.			
А	0.900	1.150			
A1	0.000	0.100			
A2	0.900	1.050			
b	0.300	0.500			
С	0.080	0.150			
D	2.800	3.000			
Е	1.200	1.400			
E1	2.250	2.550			
e 0.950TYP		0.950TYP			
e1	1.800	2.000			
L		0.550REF			
L1	0.300	0.500			
θ	0°	8°			

Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- $5. \ Controlling \ dimension \ is \ millimeter, \ converted \ inch \ dimensions \ are \ not \ necessarily \ exac$



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